

MXD8642

SP4T Switch for 3G/4G Application

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General Description

The MXD8642 is a SOI SP4T switch suitable for LTE/UMTS/CDMA application. The MXD8642 features very low insertion loss, high isolation and excellent linearity performance down to 1.0V control voltage at high frequency up to 2.7GHz. In addition, this switch is able to handle high power signals up to 36dBm. The MXD8642 has internal ESD protection devices to achieve excellent ESD performances. No DC Blocking capacitors are required for all RF ports unless DC is biased externally. And the compact QFN-12L 1.8mm × 1.8mm × 0.55mm package is adopted.

Applications

- LTE,UMTS,CDMA application
- General Purpose Switching applications

Features

- Low voltage logic control:1.8V typical
- Low insertion loss: 0.35dB @ 0.9GHz
 0.40dB @ 1.9GHz
 0.45dB @ 2.7GHz
- P0.1dB 36dBm
- Ultra small package,
 QFN-12L (1.8mm × 1.8mm × 0.55mm)

Functional Block Diagram and Pin Function

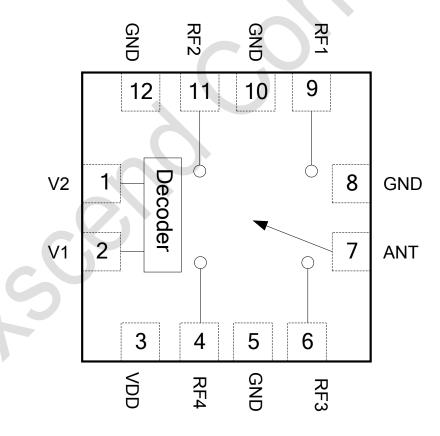


Figure 1 Functional Block Diagram and pin out



Application Circuit

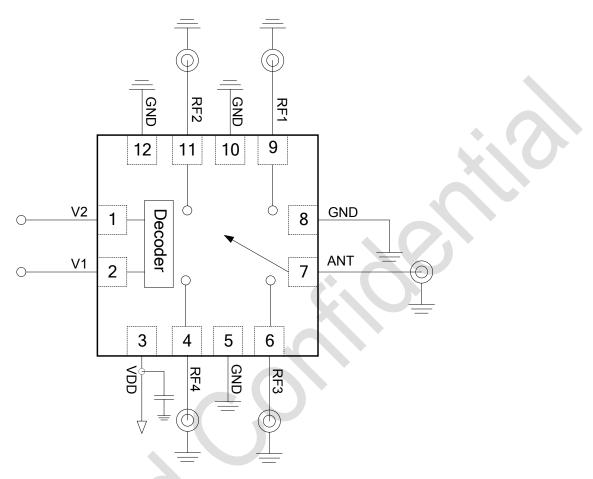


Figure 2 MXD8642 Pin Diagram

Table 1. Pin Description

| Pin No. | Name | Description | Pin No. | Name | Description |
|---------|------|-------------------|---------|------|----------------------|
| 1 | V2 | Control Logic #2 | 7 | ANT | RF signal in Antenna |
| 2 | V1 | Control Logic #1 | 8 | GND | RF and DC Ground |
| 3 | VDD | Power Supply | 9 | RF1 | RF Input / Output |
| 4 | RF4 | RF Input / Output | 10 | GND | RF and DC Ground |
| 5 | GND | RF and DC Ground | 11 | RF2 | RF Input / Output |
| 6 | RF3 | RF Input / Output | 12 | GND | RF and DC Ground |

Table 2.Truth Table

| V 1 | V2 | Path |
|------------|----|---------|
| Н | L | ANT-RF1 |
| | Н | ANT-RF2 |
| Н | Н | ANT-RF3 |
| L | Ĺ | ANT-RF4 |



Absolute Maximum Ratings

Table 3. Maximum ratings

| Parameters | Symbol | Minimum | Maximum | Units |
|--|------------------|---------|---------|--------------|
| Supply voltage | Vdd | +2.5 | +3.0 | V |
| Digital control voltage | V _{CTL} | 0 | +3.0 | V |
| RF input power | PIN | | +36 | dBm |
| Operating temperature | TOP | -20 | +85 | °C |
| Storage temperature | T _{STG} | -55 | +150 | °C |
| Electrostatic Discharge Human body model (HBM), Class 1C | ESD_HBM | | 1000 | \mathbf{S} |
| Machine Model (MM), | ESD_MM | | 100 | V |
| Class A | | | | |
| Charged device model (CDM), Class III | ESD_CDM | | 500 | |

Note: Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.

Recommended Operation Range

Table 4. Recommended operation condition

| Parameters | Symbol | Min | Тур | Max | Units |
|------------------------|-------------------|-----|-----|-----|-------|
| Operation Frequency | f1 | 0.1 | - | 3.0 | GHz |
| Power supply | V _{DD} | 2.5 | 2.8 | 3.0 | V |
| Supply current, | IDD | - | 50 | 70 | μA |
| Control voltage – High | Vctlh | 1.0 | 1.8 | Vdd | V |
| Control voltage – Low | V _{CTLL} | 0 | 0 | 0.3 | V |
| Control current - High | Ictlh | | | 5 | μA |
| Control current - Low | ICTLL | | | 5 | μA |
| | | | | | |

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Specifications

Table 5. Electrical Specifications

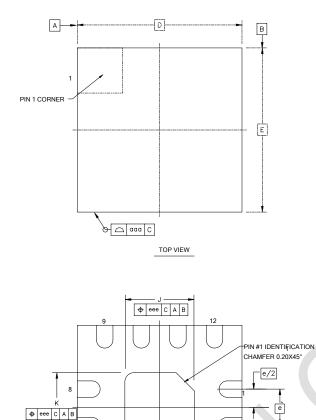
Nominal conditions unless otherwise specified. V_{DD} = 2.8 V, V_1 & V_2 = 1.8V / 0V, Temp = 25°C, 50 Ω .

SCI

| Denemeter | 0 | Specification | | | Tast Oan litian | | |
|--|-----------------------|----------------|----------------------|----------|-----------------|--|--|
| Parameter | Sym | Min. | Тур | Max. | Units | Test Condition | |
| Switching Time | | | | • | | | |
| Start-up time | t _{start-up} | - | 1 | 10 | μs | 50% V_{DD} to large signal fully compliant | |
| ON Switching speed | Ton | - | 1 | 5 | μs | 50% control to 90% RF ON | |
| OFF Switching speed | T _{off} | - | 1 | 5 | μs | 50% control to 90% RF ON | |
| Supply current | IDD | - | 50 | 70 | μA | Vdd= 2.8 V, Vctl = Vctl_h | |
| RF Specifications | | <u>.</u> | | <u> </u> | 1 | | |
| Insertion loss 1/2/3/4 | IL | - | 0.35 0.40 0.45 | | dB dB dB | 900 MHz 1900 MHz 2700 MHz | |
| Isolation 1/2/3/4 | ISO | 35 30 25 | 40 35 28 | - | dB dB dB | 900 MHz 1900 MHz 2700 MHz | |
| Pin at 0.1dB compression point | P _{0.1dB} | - | +36 | - | dBm | 0.7 GHz to 3 GHz | |
| 2 nd Harmonic | 2f0 | - | -80 | -70 | dBc | 900MHz, +34dBm | |
| 3rd Harmonic | 3f0 | - | -75 | -70 | dBc | 900MHz, +34dBm | |
| 3rd intercept point1 3rd intercept point2 | IIP3(1) IIP3(2) | +65 +63 | +70 +65 | - | dBm | 829+849 MHz , Pin = +24dBm 1870+1910 MHz , Pin = +24dBm | |

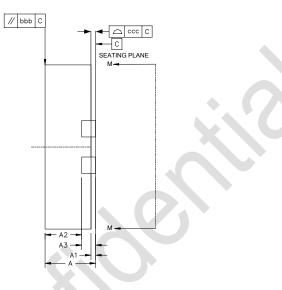


Package Outline Dimension



7

BOTTOM VIEW VIEW M-M



| DECODURTION | SYMBOL | MILLIMETER | | | | |
|-------------------|------------|------------|-----------|----------|------|--|
| DESCRIPTION | STIVIDOL | MIN | NOM | MAX | | |
| TOTAL THICKNESS | | A | 0.50 | 0.55 | 0.60 | |
| STAND OFF | A1 | 0 | | 0.05 | | |
| MOLD THICKNESS | | A2 | 0.35 | 0.40 | 0.45 | |
| L/F THICKNESS | | A3 | 0.152 REF | | | |
| LEAD WIDTH | b | 0.13 | 0.18 | 0.23 | | |
| BODY SIZE | Х | D | 1.70 | 1.80 | 1.90 | |
| BODY SIZE | Y | E | 1.70 | 1.80 | 1.90 | |
| LEAD PITCH | LEAD PITCH | | | 0.40 BSC | | |
| FP SIZE | Х | J | 0.71 | 0.76 | 0.81 | |
| EP SIZE | Y | к | 0.71 | 0.76 | 0.81 | |
| LEAD LENGTH | L | 0.20 | 0.25 | 0.30 | | |
| PACKAGE EDGE TOLE | ааа | 0.100 | | | | |
| MOLD FLATNESS | bbb | 0.100 | | | | |
| COPLANARITY | ccc | 0.080 | | | | |
| LEAD OFFSET | ddd | 0.100 | | | | |
| EXPOSED PAD OFFSE | eee | 0.100 | | | | |

Figure 3 Package outline dimension

12XL

EXPOSED DIE ATTACH PAD



Reflow Chart

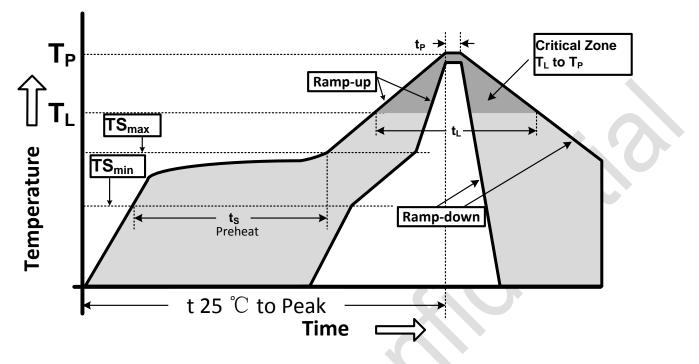


Figure 4 Recommended Lead-Free Reflow Profile

Table 6. Reflow condition

| Profile Parameter | Lead-Free Assembly,Convection,IR/Convection |
|---|---|
| Ramp-up rate (TS _{max} to T _p) | 3°C/second max. |
| Preheat temperature (TSmin to TSmax) | 150℃ to 200℃ |
| Preheat time (t _s) | 60 - 180 seconds |
| Time above TL , 217°C (t _L) | 60 - 150 seconds |
| Peak temperature (T _p) | 260 ℃ |
| Time within 5 $^{\circ}$ C of peak temperature(t _P) | 20 - 40 seconds |
| Ramp-down rate | 6℃/second max. |
| Time 25°C to peak temperature | 8 minutes max. |

ESD Sensitivity

Integrated circuits are ESD sensitive and can be damaged by static electric charge. Proper ESD protection techniques should be used when handling these devices.

RoHS Compliant

This product does not contain lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE), and are considered RoHS compliant.

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